PCN Number:	20150211	000A			P	CN Date: 03/30/2015	
Title: Qualifica	ation of Car	rier Tape for 14/3	16 pin SOP an	d 28 pi	n S	SOP device	
Customer Conta		anager Dept:		y Servi			
				nated			
Proposed 1 st Shi	p Date:	09/30/2015		Avai		-	
Change Type:							
Assembly Site	Э	Desigr	า			Wafer Bump Site	
Assembly Process			Data Sheet			Wafer Bump Material	
Assembly Ma	terials	Part n	Part number change			Wafer Bump Process	
Mechanical Specification			Test Site			Wafer Fab Site	
Packing/Ship	ping/Labelir	ng 📃 Test P	Test Process			Wafer Fab Materials	
						Wafer Fab Process	
		PCN	l Details				
Description of C	hange:						
devices are the fro for these new dev This notification is	om the Orig ices will be to inform o	inal device list of 180 days from th of TI's Qualification	f this notificati his notice for f on of change f	ion. The these n	<mark>e ex</mark> ewl [:] rier	in yellow. Group 2 pected first shipment date y added devices only. Tape 4135168-0070 ape comparison as follows:	
Carrier Tape Cou		ant		Bron			
Item	Curr	ent		Prop	ose	a	
Supplier	Cpak			Cpak			
Material	Polys	Polystyrene		Polystyrene			
Color	Black	Black		Black			
Dimension (detail compariso table 2 in sheet 4	n in B0 = k) K0 = K1 =	$A0 = 8.60n$ $10.40mm \pm 0.1$ $B0 = 10.50$ $2.5mm \pm 0.1$ $K0 = 2.50m$ $2.1mm \pm 0.1$ $K1 = 1.95n$ $6.0mm \pm 0.3$ $W = 16.00n$		0mm ± 0.1 mm ± 0.1 mm ± 0.1			
		-	to 8.12 x 10^5 Between 1.54x10 ⁵ to 5.37 x 10^6		0.00	mm ± 0.3	
Surface resistivity	Betwe	en 1.01x 10 ⁵ to	8.12 x 10 ⁵				
Surface resistivity Part number		een 1.01x 10 ⁵ to	8.12 x 10 ⁵		en 1	1.54x10 ⁵ to 5.37 x 10 ⁶	
Part number	41351		8.12 x 10 ⁵	Betwee	en 1	1.54x10 ⁵ to 5.37 x 10 ⁶	
Part number Reason for Chan Continuity of supp during Tape and F	41351 ige: bly. Tape Sig Reel process	168-0070 de pocket reflecti	ion causing hi	Betwee 421258 gh reje	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated impo	41351 ige: bly. Tape Sig Reel process	168-0070 de pocket reflecti	ion causing hi	Betwee 421258 gh reje	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated important	41351 hge: bly. Tape Sid Reel process act on Form	168-0070 de pocket reflecti s. m, Fit, Function	ion causing hi , Quality or l	Betwee 421258 gh rejea Reliabi	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated important	41351 hge: bly. Tape Sid Reel process act on Form	168-0070 de pocket reflecti s. m, Fit, Function	ion causing hi , Quality or l	Betwee 421258 gh rejea Reliabi	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated impo None Changes to prod None	41351 age: oly. Tape Sid Reel process act on Form luct identif	168-0070 de pocket reflecti s. m, Fit, Function fication resultir	ion causing hi a, Quality or bg from this	Betwee 421258 gh rejea Reliabi	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated impo None Changes to prod None	41351 age: oly. Tape Sid Reel process act on Form luct identif	168-0070 de pocket reflecti s. m, Fit, Function fication resultir	ion causing hi a, Quality or bg from this	Betwee 421258 gh rejea Reliabi	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated impo None Changes to prod None Product Affected CD4093BQNSRG	41351 age: bly. Tape Sid act on Form luct identif d Group 1: 4HT TPIC	168-0070 de pocket reflecti s. m, Fit, Function fication resultir Additional Dev 246L01DBG4	ion causing hi a, Quality or ag from this rice TPIC46L02	Betwee 421258 gh rejea Reliabi PCN:	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality v (positive / negative): TPIC46L03DB	
Part number Reason for Chan Continuity of supp during Tape and R Anticipated impa None Changes to prod None Product Affected CD4093BQNSRG TPIC46L01DB	41351 bly. Tape Sic Reel process act on Form luct identif d Group 1: 4HT TPIC	168-0070 de pocket reflecti s. m, Fit, Function fication resultir Additional Dev 246L01DBG4 246L01DBR	ion causing hi a, Quality or b ag from this vice TPIC46L02 TPIC46L02	Betwee 421258 gh rejea Reliabi PCN:	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality r (positive / negative):	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated impa None Changes to prod None Product Affected CD4093BQNSRG TPIC46L01DB	41351 bly. Tape Sic cel process act on Form luct identif d Group 1: 4HT TPIC TPIC d Group 2:	de pocket reflecti s. m, Fit, Function fication resultir Additional Dev 246L01DBG4 246L01DBR Original Device	ion causing hi a, Quality or b ag from this vice TPIC46L02 TPIC46L02	Betwee 421258 gh rejea Reliabi PCN:	en 1 89-0 ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality v (positive / negative): TPIC46L03DB	
Part number Reason for Chan Continuity of supp during Tape and F Anticipated impo None Changes to prod None Product Affected CD4093BQNSRG	41351 age: bly. Tape Sid act on Form luct identif d Group 1: 4HT TPIC d Group 2:	168-0070 de pocket reflecti s. m, Fit, Function fication resultir Additional Dev 246L01DBG4 246L01DBR	ion causing hi a, Quality or b ag from this vice TPIC46L02 TPIC46L02	Betwee 421258 gh rejea Reliabi PCN: DB DBG4	ctio	1.54x10 ⁵ to 5.37 x 10 ⁶ 0026 n rate on lead abnormality v (positive / negative): TPIC46L03DB	

Qualification Data



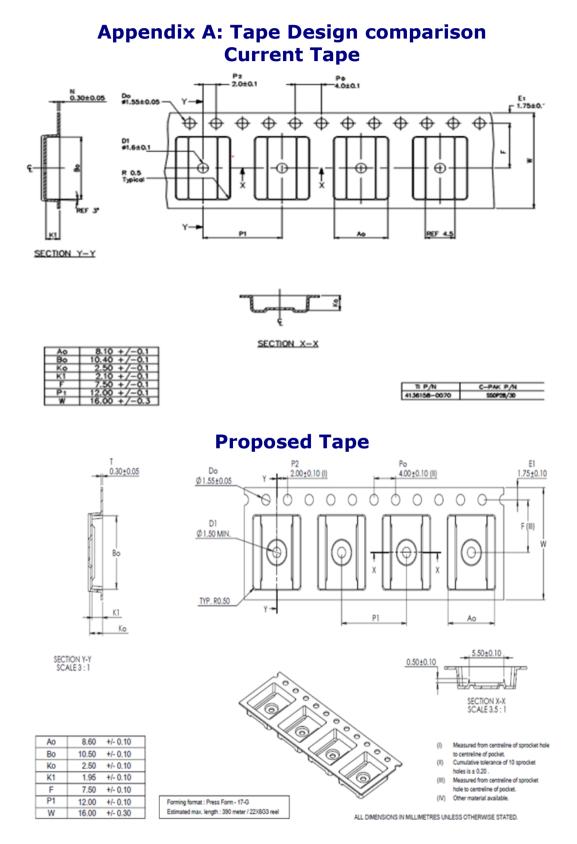
Revision: C	
EQ# :	
A/T Site:	MLA

Lead Package Carrier Tape Qualification Summary

Reference (QSS 003-008, 009-006, 014-102, 007-102)

Supplier:	C-PAK PTE LTD	
Supplier Part No:	S406031119-01	
TI Part No:	4212589-0026	(If available)
Weight/meter (g):	4.8 gm	
Material:	14 NS	
Package Description:	SOP	
Package Designator:	SSOP 28H6 CL3 22X6G3 L390 W16	
Result:	PASS	
Date:	August 19, 2014	

I. First Article Inspection Test	PASS	(Pass/Fail)
II. Manufacturability Test	PASS	
III. Dimensional Test	PASS	
IV. Camber Test	PASS	
V. Electrical Test	PASS	
VI. Fit Analysis	PASS	
VII. Drop Test	PASS	



For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Texas Instruments, Inc.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
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